



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSZ068N06NS	Issued	14. February 2022
MA#	MA005625868		
Package	PG-TSDSON-8-36	Weight*	35.40 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.386	1.09	1.09	10904	10904
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		103	
	non noble metal	zinc	7440-66-6	0.015	0.04		414	
	non noble metal	iron	7439-89-6	0.293	0.83		8281	
	non noble metal	copper	7440-50-8	11.903	33.62	34.50	336224	345022
wire	noble metal	gold	7440-57-5	0.030	0.08	0.08	839	839
encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		992	
	plastics	epoxy resin	-	1.615	4.56		45622	
	inorganic material	silicondioxide	60676-86-0	15.906	44.95	49.61	449278	495892
leadfinish	non noble metal	tin	7440-31-5	0.420	1.19	1.19	11876	11876
plating	noble metal	silver	7440-22-4	0.003	0.01	0.01	89	89
solder	noble metal	silver	7440-22-4	0.015	0.04		423	
	non noble metal	tin	7440-31-5	0.030	0.08		846	
	non noble metal	lead	7439-92-1	0.554	1.57	1.69	15652	16921
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			36	
	non noble metal	zinc	7440-66-6	0.005	0.01		142	
	non noble metal	iron	7439-89-6	0.101	0.28		2843	
	non noble metal	copper	7440-50-8	4.087	11.54	11.83	115436	118457
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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